

S/N TBD  
Docket: CS02-101  
Group art unit : \_\_\_ TBD

Date 12/11/2003

To: Commissioner of Patents and Trademarks  
P.O. Box 1450 Alexandria, VA 22313-1450

Fr: William J. Stoffel Reg. No. 39,390 Cust No. 30402  
PMB 455  
1735 Market St - Suite A  
Philadelphia, PA 19103

Subject:

Serial No. TBD  
Docket cs02-101  
File Date: with application  
Inventor: Zhang et al.

**Title: Structure and Method For Fabricating a Bond  
Pad Structure**

Group art unit: TBD

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO A820 (also PTO-1449), Information  
Disclosure Citation and references.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the  
United States Postal Service as first class mail or express mail in an  
envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria,  
VA 22313-1450, on Dec 13, 2003.

Signature/Date William J. Stoffel

William J. Stoffel Reg. No. 39,390  
Customer number 30402

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The following Patents and/or Publication are submitted to  
comply with the duty to disclose under CFR 1.97-1.99 and 37  
CFR 1.56.

US 5,084,752(Satoh et al.) shows a bonding pad.

US 4,636,823(Abe) shows a bond pad.

US 5,149,674(Freeman, Jr. et al.) shows bond pad.

US 5,751,065(Chittipeddi et al.) shows a bond pad.

US 5,923,088(Shiue et al.) shows a bond pad structure.

US 6,020,647(Skala et al) reveals a bond pad structure.

US 5,502,337(Nozaki) shows a structure of a bonding pad.

Sincerely,



William J. Stoffel  
Reg. No. 39,390  
Customer number 30,402

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>	Docket Number (Optional) <b>cs02-101</b>	Application Number
	Applicant(s) <b>Zhang et al.</b>	
	Filing Date	Group Art Unit

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		US 5,084,752		Satoh et al.			
		US 4,636,823		Abe			
		US 5,149,674		Freeman, Jr. et al.			
		US 5,751,065		Chittipeddi et al.			
		US 5,923,088		Shiue et al.			
		US 6,020,647		Skala et al			
		US 5,502,337		Nozaki			

**FOREIGN PATENT DOCUMENTS**

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

**OTHER DOCUMENTS** *(Including Author, Title, Date, Pertinent Pages, Etc.)*


EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.